Integrated Device Technology, Inc.
6024 Silver Creek Valley Road, San Jose, CA 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **PA1410-01** DATE: November 11, 2014

Product Affected: P9036-0NTGI, P9036-0NTGI8
P9036A-0NTGI, P9036A-0NTGI8

Date Effective: February 11, 2015

MEANS OF DISTINGUISHING CHANGED DEVICES:

- ■ Product Mark Change in ordering part#
- ☐ Back Mark
- ☐ Date Code
- ☐ Other

Contact: IDT PCN DESK

E-mail: pcndesk@idt.com

Attachment: ■ Yes ☐ No

Samples: Please contact your local sales representative for sample request.

DESCRIPTION AND PURPOSE OF CHANGE:

- ☐ Die Technology
- ☐ Wafer Fabrication Process
- ☐ Assembly Process
- ☐ Equipment
- ☐ Material
- ☐ Testing
- ☐ Manufacturing Site
- ☐ Data Sheet
- ■ Other - Die Revision Change

This notification is to advise our customers of a silicon die revision. The current die revision A will be changed to revision B with a change in the orderable part number and device top mark.

The new die revision is fully hardware and specification compatible with the previous revision.

There is no change to thermal and MSL specification due to this die revision.

This is no change to the die technology or process. The die change is minor.

IDT requests customers to use B revision in their newer design/projects and switch existing design/projects to B revision as soon as possible. Last time buy for revision A will be on February 11, 2015.

RELIABILITY/QUALIFICATION SUMMARY:

There is no change in die technology/process.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.
IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____ ☐ ***Approval for shipments prior to effective date.***

Name/Date: _____ E-Mail Address: _____

Title: _____ Phone # /Fax #: _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE: _____

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PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT I - PCN #: PA1410-01

PCN Type: Die Revision Change

Data Sheet Change: No

Detail of Change:

This notification is to advise our customers of a silicon die revision. The current die revision A will be changed to revision B with a change in the orderable part number and device top mark.

Revision B has the following improvements and design enhancements/features:

1) Significant EMI improvement.

2) More reliable EEPROM booting.

3) Increased design margins.

4) Better manufacturing yield and testability

5) Increased over current trip level to avoid unnecessary over-current limiting that may happen with unusual loads.

The new die revision is fully hardware and specification compatible with the previous revision.

There is no change to thermal and MSL specification due to this die revision.

This is no change to the die technology or process. The die change is minor.

IDT requests customers to use B revision in their newer design/projects and switch existing design/projects to B revision as soon as possible. Last time buy for revision A will be on February 11, 2015.

Table 1

Old Ordering Part Number	New Ordering Part Number
P9036-0NTGI	P9036BNTGI
P9036-0NTGI8	P9036BNTGI8
P9036A-0NTGI	P9036BNTGI
P9036A-0NTGI8	P9036BNTGI8

Integrated Device Technology, Inc.

Qualification Report

Date: 10/28/2014

Product Type: IDTP9036B (Wireless Power Transmitter)			
Device Family:	AW571T005ZNA	**Process Technology:**	0.25um, 40V BCD
Package Type:	NTG48 (QFN)	**Fab Location:**	TSMC, Taiwan

Test Description	Conditions	Sample Size	Reject	Comments
Device Characterization	IDT's datasheet conditions	33	0	Pass
ESD: Human Body Model	JESD22-A114 (JS-001) Classification	3	0	Pass
ESD: Charged Device Model	JESD22-C101 Classification	3	0	Pass
Latch-Up	JESD78	3	0	Pass
Temperature Cycling	JESD22-A104, -55°C to 125°C, 700 cycles	25 x 1 lot	0	Pass[1]
High Temperature Storage Life	JESD22-A103, +150 °C, 1000 hrs	25 x 1 lot	0	Pass[1]
Highly Accelerated Temperature and Humidity Stress (Biased)	JESD22-A110, +130 °C, 85% R.H., Vcc max, 100 hrs	25 x 1 lot	0	Pass[1]
Moisture Classification	J-STD-020	25 x 2 lots	0	Pass[1]
Data Retention	JESD47G-01	1 wafer	0	Pass[1]
Read Cycle	JESD47G-01	1 wafer	0	Pass[1]

Note 1: Qualification by similarity of product IDTP9030